


AMENDMENTS

In the Claims

1. (Canceled)
2. (Currently amended) A semiconductor light-emitting device constituted by mounting a semiconductor light-emitting element on a base substance, wherein

the semiconductor light-emitting element has outgoing light having an emission wavelength of 390 to 420 nm; and

there is included a fluorescent substance that is excited by outgoing light from the semiconductor light-emitting element and emits red light having an emission wavelength with its main emission peak in a wavelength range of 600 to 670 nm

 ~~The semiconductor light-emitting device according to Claim 1~~, wherein the fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$M_2 O_2 S : Eu$ (M is any one or more elements selected from La, Gd and Y);

$0.5 MgF_2 \cdot 3.5 MgO \cdot GeO_2 : Mn$;

$Y_2 O_3 : Eu$;

$Y(P, V) O_4 : Eu$; and

$YVO_4 : Eu$.

3. (Canceled)
4. (Currently amended) A semiconductor light-emitting device constituted by mounting a semiconductor light-emitting element on a base substance, wherein

the semiconductor light-emitting element has outgoing light having an emission wavelength in a range of 390 to 420 nm; and

there is included a fluorescent substance that is excited by outgoing light from the semiconductor light-emitting element and emits green light having an emission wavelength with its main emission peak in a wavelength range of 500 to 540 nm

~~The semiconductor light-emitting device according to Claim 3~~, wherein the fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$\text{RMg}_2\text{Al}_{16}\text{O}_{27} : \text{Eu, Mn}$ (R is any one or both elements selected from Sr and Ba);

$\text{RMgAl}_{10}\text{O}_{17} : \text{Eu, Mn}$ (R is any one or both elements selected from Sr and Ba);

$\text{ZnS} : \text{Cu}$;

$\text{SrAl}_2\text{O}_4 : \text{Eu}$;

$\text{SrAl}_2\text{O}_4 : \text{Eu, Dy}$;

$\text{ZnO} : \text{Zn}$;

$\text{Zn}_2\text{Ge}_2\text{O}_4 : \text{Mn}$;

$\text{Zn}_2\text{SiO}_4 : \text{Mn}$; and

$\text{Q}_3\text{MgSi}_2\text{O}_8 : \text{Eu, Mn}$ (Q is any one or more elements selected from Sr, Ba and Ca).

5. (Canceled)

6. (Currently amended) A semiconductor light-emitting device constituted by mounting a semiconductor light-emitting element on a base substance, wherein

the semiconductor light-emitting element has outgoing light having an emission wavelength in a range of 390 to 420 nm; and

there is included a fluorescent substance that is excited by outgoing light from the semiconductor light-emitting element and emits blue light having an emission wavelength with its main emission peak in a wavelength range of 410 to 480 nm

~~The semiconductor light-emitting device according to Claim 5~~, wherein the fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

cmf
A1
 $A_{10}(PO_4)_6Cl_2 : Eu$ (A is any one or more elements selected from Sr, Ca, Ba, Mg and Ce);

$XMg_2Al_6O_{27} : Eu$ (X is any one or both elements selected from Sr and Ba);

$XMgAl_{10}O_{17} : Eu$ (X is any one or both elements selected from Sr and Ba);

$ZnS : Ag$;

$Sr_{10}(PO_4)_6Cl_2 : Eu$;

$Ca_{10}(PO_4)_6F_2 : Sb$;

$Z_3MgSi_2O_8 : Eu$ (Z is any one or more elements selected from Sr, Ca and Ba);

$SrMgSi_2O_8 : Eu$;

$Sr_2P_2O_7 : Eu$; and

$CaAl_2O_4 : Eu, Nd$.

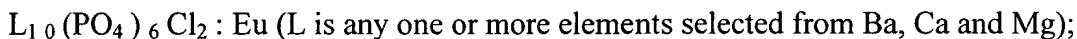
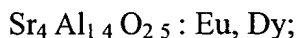
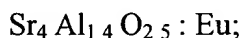
7. (Canceled)

8. (Currently amended) A semiconductor light-emitting device constituted by mounting a semiconductor light-emitting element on a base substance, wherein

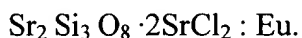
the semiconductor light-emitting element has outgoing light having an emission wavelength in a range of 390 to 420 nm; and

there is included a fluorescent substance that is excited by outgoing light from the semiconductor light-emitting element and emits blue green light having an emission wavelength with its main emission peak in a wavelength range of 480 to 500 nm

~~The semiconductor light-emitting device according to Claim 7, wherein the fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:~~



and



9. (Original) A semiconductor light-emitting device constituted by mounting a semiconductor light-emitting element on a base substance, wherein

the semiconductor light-emitting element has outgoing light having an emission wavelength in a range of 390 to 420 nm; and

there is included a fluorescent substance that is excited by outgoing light from the semiconductor light-emitting element and emits orange light having an emission wavelength with its main emission peak in a wavelength range of 570 to 600 nm.

10. (Original) The semiconductor light-emitting device according to Claim 9, wherein the fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

ZnS: Mn; and

ZnS: Cu, Mn, Co.

11. (Currently amended) The semiconductor light-emitting device according to Claim ~~[[1]]~~ 2, wherein

a sealing resin for sealing at least a part of the base substance and the semiconductor light-emitting element is included; and

the sealing resin contains the fluorescent substance.

12. (Currently amended) The semiconductor light-emitting device according to Claim ~~[[3]]~~ 4, wherein

a sealing resin for sealing at least a part of the base substance and the semiconductor light-emitting element is included; and

the sealing resin contains the fluorescent substance.

13. (Currently amended) The semiconductor light-emitting device according to Claim ~~[[5]]~~ 6, wherein

a sealing resin for sealing at least a part of the base substance and the semiconductor light-emitting element is included; and

the sealing resin contains the fluorescent substance.

14. (Currently amended) The semiconductor light-emitting device according to Claim [[7]] 8, wherein

a sealing resin for sealing at least a part of the base substance and the semiconductor light-emitting element is included; and

the sealing resin contains the fluorescent substance.

15. (Original) The semiconductor light-emitting device according to Claim 9, wherein

a sealing resin for sealing at least a part of the base substance and the semiconductor light-emitting element is included; and

the sealing resin contains the fluorescent substance.

16. (Original) The semiconductor light-emitting device according to Claim 11, wherein

the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding; and

at least a part of the two lead frames and the semiconductor light-emitting element are sealed with the sealing resin.

17. (Original) The semiconductor light-emitting device according to Claim 11, wherein

the base substance is an insulator connected to ends of a pair of lead frames;

the semiconductor light-emitting element is connected to metallic wiring formed on the insulator; and

at least a part of the pair of lead frames, the insulator and the semiconductor light-emitting element are sealed with the sealing resin.

18. (Currently amended) The semiconductor light-emitting device according to Claim ~~[[1]]~~ 2, wherein

the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;

the fluorescent substance is filled in the cup-shaped mount section; and

at least a part of the two lead frames, the semiconductor light-emitting element and the fluorescent substance are sealed with a sealing resin.

19. (Currently amended) The semiconductor light-emitting device according to Claim ~~[[3]]~~ 4, wherein

the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;

the fluorescent substance is filled in the cup-shaped mount section; and

at least a part of the two lead frames, the semiconductor light-emitting element and the fluorescent substance are sealed with a sealing resin.

20. (Currently amended) The semiconductor light-emitting device according to Claim ~~[[5]]~~ 6, wherein

the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;

the fluorescent substance is filled in the cup-shaped mount section; and

at least a part of the two lead frames, the semiconductor light-emitting element and the fluorescent substance are sealed with a sealing resin.

21. (Currently amended) The semiconductor light-emitting device according to Claim [[7]] 8, wherein

the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;

the fluorescent substance is filled in the cup-shaped mount section; and

at least a part of the two lead frames, the semiconductor light-emitting element and the fluorescent substance are sealed with a sealing resin.

22. (Original) The semiconductor light-emitting device according to Claim 9, wherein

the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;

the fluorescent substance is filled in the cup-shaped mount section; and

at least a part of the two lead frames, the semiconductor light-emitting element and the fluorescent substance are sealed with a sealing resin.

23. (Currently amended) The semiconductor light-emitting device according to Claim ~~[[1]]~~ 2, wherein

the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;

a coating member is filled in the cup-shaped mount section and the fluorescent substance is disposed on the coating member; and

at least a part of the two lead frames, the semiconductor light-emitting element, the coating member and the fluorescent substance are sealed with a sealing resin.

24. (Currently amended) The semiconductor light-emitting device according to Claim ~~[[3]]~~ 4, wherein

the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;

a coating member is filled in the cup-shaped mount section and the fluorescent substance is disposed on the coating member; and

at least a part of the two lead frames, the semiconductor light-emitting element, the coating member and the fluorescent substance are sealed with a sealing resin.

25. (Currently amended) The semiconductor light-emitting device according to Claim ~~[[5]]~~ 6, wherein

the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;

a coating member is filled in the cup-shaped mount section and the fluorescent substance is disposed on the coating member; and

at least a part of the two lead frames, the semiconductor light-emitting element, the coating member and the fluorescent substance are sealed with a sealing resin.

26. (Currently amended) The semiconductor light-emitting device according to Claim [[7]] 8, wherein

the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;

a coating member is filled in the cup-shaped mount section and the fluorescent substance is disposed on the coating member; and

at least a part of the two lead frames, the semiconductor light-emitting element, the coating member and the fluorescent substance are sealed with a sealing resin.

27. (Original) The semiconductor light-emitting device according to Claim 9, wherein

the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;

a coating member is filled in the cup-shaped mount section and the fluorescent substance is disposed on the coating member; and

at least a part of the two lead frames, the semiconductor light-emitting element, the coating member and the fluorescent substance are sealed with a sealing resin.

28. (Currently amended) The semiconductor light-emitting device according to Claim [[1]] 2, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected the metallic wiring on the substrate;

a sealing resin for sealing the semiconductor light-emitting element is included; and

the sealing resin contains the fluorescent substance.

29. (Currently amended) The semiconductor light-emitting device according to Claim [[3]] 4, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected the metallic wiring on the substrate;

a sealing resin for sealing the semiconductor light-emitting element is included; and

the sealing resin contains the fluorescent substance.

30. (Currently amended) The semiconductor light-emitting device according to Claim [[5]] 6, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected the metallic wiring on the substrate;

a sealing resin for sealing the semiconductor light-emitting element is included; and

the sealing resin contains the fluorescent substance.

31. (Currently amended) The semiconductor light-emitting device according to Claim [[7]] 8, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected the metallic wiring on the substrate;

a sealing resin for sealing the semiconductor light-emitting element is included; and

the sealing resin contains the fluorescent substance.

32. (Original) The semiconductor light-emitting device according to Claim 9, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected the metallic wiring on the substrate;

a sealing resin for sealing the semiconductor light-emitting element is included; and

the sealing resin contains the fluorescent substance.

33. (Currently amended) The semiconductor light-emitting device according to Claim [[1]] 2, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion; and

the fluorescent substance is filled in the recessed portion.

34. (Currently amended) The semiconductor light-emitting device according to Claim ~~[[3]]~~ 4, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion; and

the fluorescent substance is filled in the recessed portion.

35. (Currently amended) The semiconductor light-emitting device according to Claim ~~[[5]]~~ 6, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion; and

the fluorescent substance is filled in the recessed portion.

36. (Currently amended) The semiconductor light-emitting device according to Claim ~~[[7]]~~ 8, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion; and

the fluorescent substance is filled in the recessed portion.

37. (Original) The semiconductor light-emitting device according to Claim 9, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion; and

the fluorescent substance is filled in the recessed portion.

38. (Original) The semiconductor light-emitting device according to Claim 33, wherein

the recessed portion is formed by a frame disposed on the substrate.

39. (Currently amended) The semiconductor light-emitting device according to Claim [[1]] 2, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion;

a sealing resin is filled in the recessed portion; and

the fluorescent substance is disposed on the sealing resin.

40. (Currently amended) The semiconductor light-emitting device according to Claim [[3]] 4, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion;

a sealing resin is filled in the recessed portion; and

the fluorescent substance is disposed on the sealing resin.

41. (Currently amended) The semiconductor light-emitting device according to Claim [[5]] 6, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion;

a sealing resin is filled in the recessed portion; and

the fluorescent substance is disposed on the sealing resin.

42. (Currently amended) The semiconductor light-emitting device according to Claim [[7]] 8, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion;

a sealing resin is filled in the recessed portion; and

the fluorescent substance is disposed on the sealing resin.

43. (Original) The semiconductor light-emitting device according to Claim 9, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion;

a sealing resin is filled in the recessed portion; and

the fluorescent substance is disposed on the sealing resin.

44. (Currently amended) The semiconductor light-emitting device according to Claim [[1]] 2, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

the fluorescent substance is contained in the sealing resin.

45. (Currently amended) The semiconductor light-emitting device according to Claim [[3]] 4, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

the fluorescent substance is contained in the sealing resin.

46. (Currently amended) The semiconductor light-emitting device according to Claim ~~[[5]]~~ 6, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

the fluorescent substance is contained in the sealing resin.

47. (Currently amended) The semiconductor light-emitting device according to Claim ~~[[7]]~~ 8, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

the fluorescent substance is contained in the sealing resin.

48. (Original) The semiconductor light-emitting device according to Claim 9, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

the fluorescent substance is contained in the sealing resin.

49. (Currently amended) The semiconductor light-emitting device according to Claim [[1]] 2, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

50. (Currently amended) The semiconductor light-emitting device according to Claim ~~[[3]]~~ 4, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

51. (Currently amended) The semiconductor light-emitting device according to Claim ~~[[5]]~~ 6, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

52. (Currently amended) The semiconductor light-emitting device according to Claim [[7]] 8, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

53. (Original) The semiconductor light-emitting device according to Claim 9, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

54. (Currently amended) The semiconductor light-emitting device according to Claim [[1]] 2, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

at least a light-emitting section of the semiconductor light-emitting element is disposed in a recessed portion in the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

55. (Currently amended) The semiconductor light-emitting device according to Claim [[3]] 4, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

at least a light-emitting section of the semiconductor light-emitting element is disposed in a recessed portion in the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

56. (Currently amended) The semiconductor light-emitting device according to Claim [[5]] 6, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

at least a light-emitting section of the semiconductor light-emitting element is disposed in a recessed portion in the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

57. (Currently amended) The semiconductor light-emitting device according to Claim [[7]] 8, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

at least a light-emitting section of the semiconductor light-emitting element is disposed in a recessed portion in the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

58. (Original) The semiconductor light-emitting device according to Claim 9, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

at least a light-emitting section of the semiconductor light-emitting element is disposed in a recessed portion in the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

59. (Currently amended) The semiconductor light-emitting device according to Claim [[1]] 2, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the sealing resin that reflects light.

60. (Currently amended) The semiconductor light-emitting device according to Claim [[3]] 4, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the sealing resin that reflects light.

61. (Currently amended) The semiconductor light-emitting device according to Claim [[5]] 6, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the sealing resin that reflects light.

62. (Currently amended) The semiconductor light-emitting device according to Claim [[7]] 8, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the sealing resin that reflects light.

63. (Original) The semiconductor light-emitting device according to Claim 9, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the sealing resin that reflects light.

64. (Canceled)

65. (Currently amended) A semiconductor light-emitting device constituted by mounting a semiconductor light-emitting element on a base substance, wherein

the semiconductor light-emitting element has outgoing light having emission wavelengths of 390 to 420 nm;

a first fluorescent substance, a second fluorescent substance and a third fluorescent substance are included;

the first fluorescent substance has red outgoing light having emission wavelengths with its main emission peak in a wavelength range of 600 to 670 nm;

the second fluorescent substance has green outgoing light having emission wavelengths with its main emission peak in a wavelength range of 500 to 540 nm;

the third fluorescent substance has blue outgoing light having emission wavelengths with its main emission peak in a wavelength range of 410 to 480 nm; and

the sum of colors of light emitted from the first, second and third fluorescent substances is a white color

~~The semiconductor light-emitting device according to Claim 64, wherein~~

the first fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

M_2O_2S : Eu (M is any one or more elements selected from La, Gd and Y);

$0.5MgF_2 \cdot 3.5MgO \cdot GeO_2$: Mn;

Y_2O_3 : Eu,

$Y(P, V) O_4 : Eu$; and

$YVO_4 : Eu$;

the second fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$RMg_2 Al_{16} O_{27} : Eu, Mn$ (R is any one or both elements selected from Sr and Ba);

$RMgAl_{10} O_{17} : Eu, Mn$ (R is any one or both elements selected from Sr and Ba);

$ZnS : Cu$;

$SrAl_2 O_4 : Eu$;

$SrAl_2 O_4 : Eu, Dy$;

$ZnO : Zn$;

$Zn_2 Ge_2 O_4 : Mn$;

$Zn_2 SiO_4 : Mn$; and

$Q_3 MgSi_2 O_8 : Eu, Mn$ (Q is any one or more elements selected from Sr, Ba and Ca);

and

the third fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$A_{10} (PO_4)_6 Cl_2 : Eu$ (A is any one or more elements selected from Sr, Ca, Ba, Mg and Ce);

$XMg_2 Al_{16} O_{27} : E$ (X is any one or both elements selected from Sr and Ba);

$\text{XMgAl}_{10}\text{O}_{17} : \text{Eu}$ (X is any one or both elements selected from Sr and Ba);

$\text{ZnS} : \text{Ag}$;

$\text{Sr}_{10}(\text{PO}_4)_6\text{Cl}_2 : \text{Eu}$;

$\text{Ca}_{10}(\text{PO}_4)_6\text{F}_2 : \text{Sb}$;

$\text{Z}_3\text{MgSi}_2\text{O}_8 : \text{Eu}$ (Z is any one or more elements selected from Sr, Ca and Ba);

$\text{SrMgSi}_2\text{O}_8 : \text{Eu}$;

$\text{Sr}_2\text{P}_2\text{O}_7 : \text{Eu}$;

$\text{CaAl}_2\text{O}_4 : \text{Eu, Nd}$.

66. (Currently amended) The semiconductor light-emitting device according to Claim [[64]] 65, wherein, assuming the total amount as 100 weight %, Cont
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the first fluorescent substance is between 50 weight % and 70 weight % inclusive;

the second fluorescent substance is between 7 weight % and 20 weight % inclusive;

and

the third fluorescent substance is between 20 weight % and 30 weight % inclusive.

67. (Original) The semiconductor light-emitting device according to Claim 66, wherein

the sealing resin contains the first, second and third fluorescent substances; and

the proportion of the total weight of the first, second and third fluorescent substances to the weight of the sealing resin is between 0.5 and 1 inclusive.

68. (Currently amended) A light-emitting display device comprising;

a light source using the semiconductor light-emitting device according to Claim [[64]] 65;

a light guiding plate for guiding light from the light source; and

red, green and blue color filters for transmitting light from the light guiding plate and dividing the light; the light-emitting display device, wherein

outgoing light from the semiconductor light-emitting device has a wavelength distribution that matches spectral characteristics of the color filters.

69. (Original) The light-emitting display device according to Claim 68, wherein at least one of the following is adjusted so that the wavelength distribution of the outgoing light from the semiconductor light-emitting device matches spectral characteristics of the color filters:

the emission wavelength of the semiconductor light-emitting element;

the emission wavelength of the first fluorescent substance;

the emission wavelength of the second fluorescent substance;

the emission wavelength of the third fluorescent substance;

the mixture proportions of the first, second and third fluorescent substances; and

the proportion of the total weight of the first, second and third fluorescent substances to the weight of the sealing resin.

70. (Original) The light-emitting display device according to Claim 68, wherein the light-emitting display device is a liquid crystal display device.

71. (Original) The light-emitting display device according to Claim 69, wherein the light-emitting display device is a liquid crystal display device.

72. (New) The semiconductor light-emitting device according to Claim 65, further comprising:

a reflector having a cross section substantially in a quarter ellipse shape for reflecting at least a part of outgoing light from the semiconductor light-emitting element; and

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector, wherein the sealing resin contains the fluorescent substance.

73. (New) The semiconductor light-emitting device according to Claim 65, further comprising:

a reflector having a cross section substantially in a quarter ellipse shape for reflecting at least a part of outgoing light from the semiconductor light-emitting element;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector; and

a layer of the fluorescent substance provided on a outside surface of the sealing resin.

74. (New) The semiconductor light-emitting device according to Claim 65, further comprising:

a reflector having a cross section substantially in a quarter ellipse shape for reflecting at least a part of outgoing light from the semiconductor light-emitting element;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector;

a layer of the fluorescent substance provided on a reflective surface of the reflector; and

a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device.

75. (New) The semiconductor light-emitting device according to Claim 65, further comprising:

a reflector having a cross section substantially in a quarter ellipse shape for reflecting at least a part of outgoing light from the semiconductor light-emitting element;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector; and

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a layer of the fluorescent substance provided on a reflective surface of the reflector, wherein the base substance is a substrate provided with a recessed portion, and at least a light-emitting section of the semiconductor light-emitting element is disposed in a recessed portion of the substrate so as not to emit light from the semiconductor light-emitting element directly to an outside of the semiconductor light-emitting device.

76. (New) A semiconductor light-emitting device constituted by mounting a semiconductor light-emitting element on a base substance, wherein the semiconductor light-emitting element has outgoing light having emission wavelengths of 390 to 420 nm; a first fluorescent substance, a second fluorescent substance and a third fluorescent substance are included;

the first fluorescent substance has red outgoing light having emission wavelengths with its main emission peak in a wavelength range of 600 to 670 nm;

the second fluorescent substance has green outgoing light having emission wavelengths with its main emission peak in a wavelength range of 500 to 540 nm;

the third fluorescent substance has blue outgoing light having emission wavelengths with its main emission peak in a wavelength range of 410 to 480 nm;

the sum of colors of light emitted from the first, second and third fluorescent substances is a white color;

the semiconductor light-emitting device further comprising:

a reflector having a cross section substantially in a quarter ellipse shape for reflecting at least a part of outgoing light from the semiconductor light-emitting element; and

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector, wherein the sealing resin contains the fluorescent substance.

77. (New) A semiconductor light-emitting device constituted by mounting a semiconductor

light-emitting element on a base substance, wherein the semiconductor light-emitting element has

outgoing light having emission wavelengths of 390 to 420 nm;

a first fluorescent substance, a second fluorescent substance and a third fluorescent substance are included;

the first fluorescent substance has red outgoing light having emission wavelengths with its main emission peak in a wavelength range of 600 to 670 nm;

the second fluorescent substance has green outgoing light having emission wavelengths with its main emission peak in a wavelength range of 500 to 540 nm;

the third fluorescent substance has blue outgoing light having emission wavelengths with its main emission peak in a wavelength range of 410 to 480 nm;

the sum of colors of light emitted from the first, second and third fluorescent substances is a white color;

the semiconductor light-emitting device further comprising:

a reflector having a cross section substantially in a quarter ellipse shape for reflecting at least a part

of outgoing light from the semiconductor light-emitting element;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector; and

a layer of the fluorescent substance provided on a outside surface of the sealing resin.

78. (New) A semiconductor light-emitting device constituted by mounting a semiconductor light-emitting element on a base substance, wherein the semiconductor light-emitting element has outgoing light having emission wavelengths of 390 to 420 nm;

a first fluorescent substance, a second fluorescent substance and a third fluorescent substance are included;

the first fluorescent substance has red outgoing light having emission wavelengths with its main emission peak in a wavelength range of 600 to 670 nm;

the second fluorescent substance has green outgoing light having emission wavelengths with its main emission peak in a wavelength range of 500 to 540 nm;

the third fluorescent substance has blue outgoing light having emission wavelengths with its main emission peak in a wavelength range of 410 to 480 nm;

the sum of colors of light emitted from the first, second and third fluorescent substances is a white color;

the semiconductor light-emitting device further comprising:

a reflector having a cross section substantially in a quarter ellipse shape for reflecting at least a part of outgoing light from the semiconductor light-emitting element;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector;

a layer of the fluorescent substance provided on a reflective surface of the reflector; and

a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device.

79. (New) A semiconductor light-emitting device constituted by mounting a semiconductor light-emitting element on a base substance, wherein the semiconductor light-emitting element has outgoing light having emission wavelengths of 390 to 420 nm;

a first fluorescent substance, a second fluorescent substance and a third fluorescent substance are included;

the first fluorescent substance has red outgoing light having emission wavelengths with its main emission peak in a wavelength range of 600 to 670 nm;

the second fluorescent substance has green outgoing light having emission wavelengths with its main emission peak in a wavelength range of 500 to 540 nm;

the third fluorescent substance has blue outgoing light having emission wavelengths with its main emission peak in a wavelength range of 410 to 480 nm;

the sum of colors of light emitted from the first, second and third fluorescent substances is a white color;

the semiconductor light-emitting device further comprising:

a reflector having a cross section substantially in a quarter ellipse shape for reflecting at least a part of outgoing light from the semiconductor light-emitting element;

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a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector; and

a layer of the fluorescent substance provided on a reflective surface of the reflector, wherein the base substance is a substrate provided with a recessed portion, and at least a light-emitting section of the semiconductor light-emitting element is disposed in a recessed portion of the substrate so as not to emit light from the semiconductor light-emitting element directly to an outside of the semiconductor light-emitting device.
